Product Change Notification / SYST-13RHMM178

Date:

19-Apr-2022

Product Category:

8-bit Microcontrollers

PCN Type:

Document Change

Notification Subject:

ERRATA - PIC18F06/16Q41 Silicon Errata and Data Sheet Clarifications Revision

Affected CPNs:

SYST-13RHMM178_Affected_CPN_04192022.pdf
SYST-13RHMM178_Affected_CPN_04192022.csv

Notification Text:

SYST-13RHMM178

Microchip has released a new Product Documents for the PIC18F06/16Q41 Silicon Errata and Data Sheet Clarifications of devices. If you are using one of these devices please read the document located at PIC18F06/16Q41 Silicon Errata and Data Sheet Clarifications.

Notification Status: Final

Description of Change:1. Updating the flash memory cell endurance specification datasheet clarification. Adding silicon erratum item 1.7.1

Impacts to Data Sheet: None

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 19 April 2022

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

PIC18F06/16Q41 Silicon Errata and Data Sheet Clarifications

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC18F06Q41-E/SL
PIC18F06Q41-E/ST
PIC18F06Q41-I/SL
PIC18F06Q41-I/ST
PIC18F06Q41T-I/SL
PIC18F06Q41T-I/ST
PIC18F16Q41-E/SS
PIC18F16Q41-E/SO
PIC18F16Q41-E/P
PIC18F16Q41-E/REB
PIC18F16Q41-I/SS
PIC18F16Q41-I/SO
PIC18F16Q41-I/P
PIC18F16Q41-I/REB
PIC18F16Q41T-I/SS
PIC18F16Q41T-I/SO

PIC18F06/16Q41

PIC18F06/16Q41 Silicon Errata and Data Sheet Clarifications

The PIC18F06/16Q41 devices you have received conform functionally to the current device data sheet (DS40002214**E**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in the table below.

The errata described in this document will be addressed in future revisions of the PIC18F06/16Q41 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current.

Table 1. Silicon Device Identification

Part Number	Device ID	Revision ID		
		A4	A5	A6
PIC18F06Q41	0x7580	0xA004	0xA005	0xA006
PIC18F16Q41	0x7560	0xA004	0xA005	0xA006

Important: Refer to the **Device/Revision ID** section in the current **"PIC18-Q41 Family Programming Specification"** (DS40002143) for more detailed information on Device Identification and Revision IDs for a specific device.

Table 2. Silicon Issue Summary

Module	Feature	Item No.	Issue Summary	Affected Revisions		
				A4	A5	A6
Analog-to-Digital Converter with Computation	ADCC	1.1.1.	ADC cannot operate in certain low-power conditions	X		
		1.1.2.	Double Sample Conversions	X	X	X
Oscillator	XT mode	1.2.1.	Maximum clock frequency limited to 2 MHz for XT mode	X		
	Fail-Safe Clock Monitor	1.2.2.	Enabling the FOSC Fail-Safe Clock Monitor alongside the Primary or Secondary Oscillator Clock Monitor causes issues in Sleep	X		
	EC mode	1.2.3.	Maximum clock frequency for EC mode is 32 MHz for V_{DD} < 2.0V	X		
I^2C	I^2C	1.3.1.	I2CxADR0/1/2/3 registers have incorrect Reset value	X		
		1.3.2.	I^2C Start and/or Stop Flags May be Set When I^2C is Enabled	X	X	

.....continued

Module	Feature	Item No.	Issue Summary	Affected Revisions		
				A4	A5	A6
Operational Amplifier	OPA	1.4.1.	Charge Pump On Control (CPON) bit is reserved	X		
	OPA	1.4.2.	Internal resistor ladder does not disconnect in Unity Gain mode	X		
Universal Asynchronous Receiver Transmitter	UART	1.5.1.	UART TXDE signal may go low before the STOP bit has been entirely transmitted.	X	X	X
		1.5.2.	Asynchronous 9-bit UART Address Mode Address Mismatch	X	X	X
Signal Measurement TImer	SMT	1.6.1.	Reset Bit	X	X	X
PIC18 CPU	FSR Shadow Registers	1.7.1.	FSR Shadow Registers are not Writable	X	X	X

Note: Only those issues indicated in the last column apply to the current silicon revision.

1. Silicon Errata Issues

CAUTION

Notice: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the bold font in the following tables apply to the current silicon revision.

1.1 Module: Analog-to-Digital Converter with Computation (ADCC)

1.1.1 ADC Cannot Operate in Certain Low-Power Conditions

The ADC will not function when all of the following conditions exist: When the MCU system clock is sourced from LFINTOSC or SOSC and when both the BOR and FVR features are disabled.

Work around

- Method 1: Use a system clock other than LFINTOSC or SOSC.
- Method 2: Enable the BOR feature.
- Method 3: Enable the FVR feature.

Affected Silicon Revisions

A4	A5	A6
X		

1.1.2 Double Sample Conversions

When enabling a Double Sample Conversion (DSEN = 1), with no Precharge time (ADPRE = 0) and no Acquisition time (ADACQ = 0), the maximum number of cycles of acquisition time is inserted prior to the second conversion. The first conversion will be performed as expected with no Precharge time and no Acquisition time. It is only between the first and second conversions where a maximum number of cycles of Acquisition time is performed unexpectedly.

Work around

- Method 1: Disable Double Sample Conversion (DSEN = 0) and perform two single conversions back to back.
- Method 2: If adding acquisition time is acceptable, then select no Precharge time, along with the desired Acquisition time.

Affected Silicon Revisions

A4	A5	A6
X	**X**	**X**

1.2 Module: Oscillator

1.2.1 Maximum Clock Frequency Limited to 2 MHz for XT Mode

The maximum clock frequency for the intermediate gain setting that supports quartz crystal and ceramic resonator operation (XT mode) is being reduced from 4 MHz to 2 MHz.

Work around

For crystal or resonator frequencies above 2 MHz, use HS mode.

Affected Silicon Revisions

A4	A5	A6
X		

1.2.2 Enabling the FOSC Fail-Safe Clock Monitor Alongside the Primary or Secondary Oscillator Clock Monitor Causes Issues with Sleep

When the FOSC Fail-Safe Clock Monitor is enabled (FCMEN Configuration bit = `1`) and either the Primary or Secondary Fail-Safe Clock Monitor is also enabled (FCMENS and/or FCMENP = `1`), putting the device to Sleep will cause a Fail-Safe condition to trigger. This has the effect of erroneously triggering Fail-Safe interrupts when there has not been a clock interruption. This can also cause the Watchdog Timer to not properly wake up the part from Sleep.

Work around
If proper functionality in Sleep is required, do not enable the Primary or Secondary Fail-Safe Clock Monitor while the FOSC Fail-Safe Clock Monitor is enabled. If Primary or Secondary Clock Monitoring in Sleep is desired, disable the FOSC Fail-Safe Clock Monitor before the device goes to Sleep.

Affected Silicon Revisions

A4	A5	A6
X		

1.2.3 Maximum Clock Frequency for EC Mode Is 32 MHz for V_{DD} < 2.0V

When configured in External Clock High-Power (ECH) mode and operating at V_{DD} < 2.0V, the maximum input clock frequency is 32 MHz.

Work around
To obtain a system clock frequency of 64 MHz in ECH mode at V_{DD} < 2.0V, use a 16 MHz external clock in conjunction with the 4x Phase-Locked Loop (PLL) circuit (i.e., either RSTOSC Configuration bits = `0b010` or OSCCON1bits.NOSC = `0b010`).

Affected Silicon Revisions

A4	A5	A6
X		

1.3 Module: I^2C

1.3.1 The I2CxADR0/1/2/3 Registers Have Incorrect Reset Value

The I2CxADR0/2 registers reset to `0xFF` when the I2CxMD is enabled instead of `0x00`. The I2CxADR1/3 registers reset to `0xFE` when the I2CxMD is enabled instead of `0x00`.

Work around
None.

Affected Silicon Revisions

A4	A5	A6
X		

1.3.2 The I²C Start and/or Stop Flags May Be Set When I²C Is Enabled

When I²C is enabled, erroneous Start and/or Stop conditions may be detected. This can generate erroneous I²C interrupts if enabled.

Work around

Use the following procedure to correctly detect the Start and Stop conditions:

1. Disable the Start and Stop conditions interrupt functions.
2. Enable the I²C module.
3. Wait 250 ns + six instructions cycles ($F_{OSC}/4$).
4. Clear the Start and Stop conditions interrupt flags.
5. Enable the Start and Stop conditions interrupt functions if used.

```
I2CxPIEbits.SCIE = 0;        // Disable Start conditoin interrupt
I2CxPIEbits.PCIE = 0;        // Disable Stop condition interrupt
I2CxCON0bits.EN = 1;         // Enable I2C
Delay();                     // Wait for 250nS + 6 instruction cycles (FOSC/4)
I2CxPIRbits.SCIF = 0;        // Clear the Start condition interrupt flags
I2CxPIRbits.PCIF = 0;        // Clear the Stop condition interrupt flags
I2CxPIEbits.SCIE = 1;        // Enable Start condition interrupt if used
I2CxPIEbits.PCIE = 1;        // Enable Stop condition interrupt if used
```

Affected Silicon Revisions

A4	A5	A6
X	X	

1.4 Module: Operational Amplifier

1.4.1 The Charge Pump On Control (CPON) Bit Is Reserved

When not operating the OPA near the rails, the Charge Pump On Control (CPON) bit can be used to disable the charge pump in order to save on current consumption. This feature is currently not available, and the charge pump is always enabled whenever the OPA module is in operation.

Work around

None.

Affected Silicon Revisions

A4	A5	A6
X		

1.4.2 Internal Resistor Ladder Does Not Disconnect in Unity Gain Mode

When using the OPA module in a unity gain configuration, the internal resistor ladder will not automatically disconnect from the operational amplifier, which may adversely affect the gain of the circuit. This applies when the peripheral has been configured to operate in Unity Gain mode in software by setting the UG bit, or in hardware using the hardware controlled override feature.

Work around

Disconnect the internal resistor ladder from the operational amplifier by writing to the Inverting Input Channel Selection (NCH) bits. All signals can be disconnected from the operational amplifier by writing `0b000` to the NCH bits.

Affected Silicon Revisions

A4	A5	A6
X		

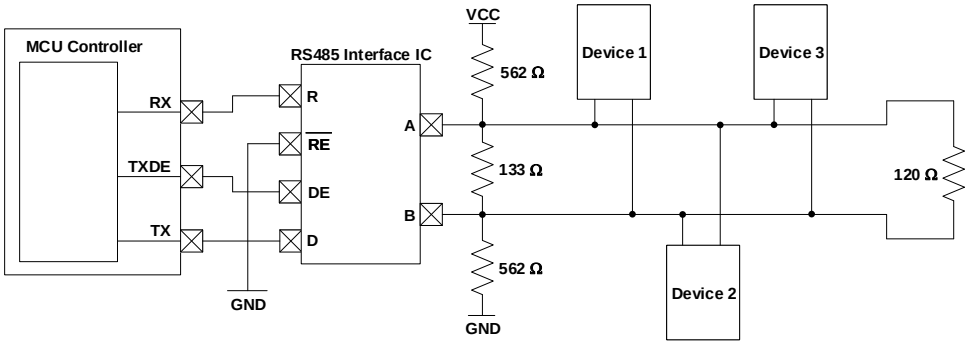
1.5 Module: Universal Asynchronous Receiver Transmitter

1.5.1 UART TXDE Signal May go Low Before The STOP Bit Has Been Entirely Transmitted.

The UART Transmit Drive Enable (TXDE) signal could potentially transition into a low state before the UART STOP bit has been entirely transmitted due to the effects of parasitic capacitance on the TX line. In some applications, this could result in communication being prematurely terminated due to the TXDE bit going low before the STOP bit has had enough time to settle.

Work around

In order to ensure that the STOP bit settles into its final logic state before the TXDE signal transitions low, a biasing circuit can be implemented. A biasing circuit allows the TX line to either be driven high or low, rather than being left in a floating tri-state mode where prolonged rise or fall times could lead to communication being disrupted. This bias circuit should only be implemented on one end of the serial bus, and a termination resistor should be used on the other end. The figure below show an example of a bias circuit that can be used to achieve this. Please note that the resistor values used in this circuit are recommendations, and that the actual resistor values required may vary based on the application.



Affected Silicon Revisions

A4	A5	A6
X	X	X

1.5.2 Asynchronous 9-bit UART Address Mode Address Mismatch

In Asynchronous 9-bit UART Address mode there is the possibility that a false address mismatch may occur even when the address of both devices match, or that a false address match may occur when there is an address mismatch between the devices.

Work around

None. Do not use the UART modules in Asynchronous 9-bit Address Mode

Affected Silicon Revisions

A4	A5	A6
X	X	X

1.6 Module: SMT

1.6.1 Reset Bit

If the SMT clock prescaler is set to any value other than '00', setting the RST bit will cause the module to stop working. The RST bit will remain at the value '1', the counter will not increment, and no interrupts will be generated. The problem is cleared by turning the module off and on, or by a device reset.

Work around

- Method 1: Do not set the RST bit; manual reset is usually not required for typical operation because the measurement logic will reset the counter automatically.
- Method 2: Write zero to the counter manually. The module enable or the clock should be disabled during this.
- Method 3: Use 1:1 prescaler (PS = 00).
- Method 4: Use the CLKREF subsystem to provide a prescaled clock and set PS = 00.

Affected Silicon Revisions

A4	A5	A6
X	X	X

1.7 Module: PIC18 Core

1.7.1 FSR Shadow Registers are not Writable

Writing to the FSR Shadow Registers does not result in accurate values being stored in the registers. Consequently, reading the FSR Shadow Registers after they have been written will return inaccurate data.

Work around

Writes to the FSR shadow registers can be performed safely using the following steps:

1. Save regular FSR2 value into RAM
2. Write the regular FSR2 with the targeted value minus the computed offset (IR[6:0] + 1, see below)
3. Write the shadow FSRxL (data doesn't matter), this will clock the shadow FSR with the FSR computed offset value.
4. Decrement FSR2 value by 1 since FSRxH increments the address by 1 (IR[6:0])
5. Write FSRxH
6. Restore the regular FSR2 from the stored RAM value.

The FSR shadow should have the value desired and the regular FSR should have the original value.

Affected Silicon Revisions

A4	A5	A6
X	X	X

2. Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS40002214**E**):

Note:

Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

2.1 Memory Programming Specifications

The flash memory cell endurance specification is reduced to **1k** minimum. The corresponding parameter (E_P) will be updated in the next revision of datasheet (DS40002214F).

Table 2-1. Memory Programming

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
Data EEPROM Memory Specifications							
MEM20	E_D	DataEE Byte Endurance	100k	—	—	E/W	-40°C ≤ T_A ≤ +85°C
MEM21	T_{D_RET}	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
MEM22	N_{D_REF}	Total Erase/Write Cycles before Refresh	1M	4M	—	E/W	-40°C ≤ T_A ≤ +85°C
MEM23	V_{D_RW}	V_{DD} for Read or Erase/Write operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM24	T_{D_BEW}	Byte Erase and Write Cycle Time	—	—	11	ms	
Program Flash Memory Specifications							
MEM30	**E_P**	**Flash Memory Cell Endurance**	**1k**	—	—	**E/W**	**-40°C ≤ T_A ≤ +85°C (Note 1)**
MEM32	T_{P_RET}	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
MEM33	V_{P_RD}	V_{DD} for Read operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM34	V_{P_REW}	V_{DD} for Row Erase or Write operation	V_{DDMIN}	—	V_{DDMAX}	V	
MEM35	T_{P_REW}	Self-Timed Page Write	—	—	10	ms	
MEM36	T_{SE}	Self-Timed Page Erase	—	—	11	ms	
MEM37	T_{P_WRD}	Self-Timed Word Write	—	—	75	µs	

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note:

1. Flash Memory Cell Endurance for the Flash memory is defined as: One Row Erase operation and one Self-Timed Write.

2.2 UART Baud Rate Equation

The UART Baud Rate equation in the UxBRG register contains a typo and will provide the incorrect UART Baud Rate. The correct equation is shown below. The correction to this equation is shown in bold.

UART Baud Rate = [Fosc*(1+(BRGS*3)]/[(16*(BRG**+**1))]

2.3 Power-Down Current (I_{PD}) Specifications

The Power-Down current (I_{PD}) electrical specifications for FVR Buffer 2, I_{PD} Base when VREGPM = `01`, and the Operational Amplifier have been modified. The corresponding parameters ($I_{PD\_FVR\_BUF2}$, I_{PD}, and I_{PD_OPA}) will be updated in the next revision of the datasheet (DS40002214F).

Table 2-2. Power-Down Current (I_{PD})(1,2)

Standard Operating Conditions (unless otherwise stated)										
Param. No.	Sym.	Device Characteristics	Min.	Typ.†	Max. +85°C	Max. +125°C	Units	Conditions		
								V_{DD}	VREGPM	Note
D200	**I_{PD}**	**I_{PD} Base**	—	1.1	3.3	4.6	µA	3.0V	`'b11`	
			—	0.9	12.1	33.3	µA	3.0V	`'b10`	
			—	**38.0**	**54.0**	**78.0**	**µA**	**3.0V**	**`'b01`**	
			—	152	190	198.5	µA	3.0V	`'b00`	
D201	I_{PD_WDT}	Low-Frequency Internal Oscillator/WDT	—	1.5	3.8	5.1	µA	3.0V	`'b11`	
D202	I_{PD_SOSC}	Secondary Oscillator (S_{OSC})	—	2.1	4.6	7.9	µA	3.0V	`'b11`	
D203	I_{PD_LPBOR}	Low-Power Brown-out Reset (LPBOR)	—	1.3	3.5	4.8	µA	3.0V	`'b11`	
D204	$I_{PD\_FVR\_BUF1}$	FVR Buffer 1 (ADC)	—	174.7	249.7	255.4	µA	3.0V	`'b11`	
D204A	**$I_{PD\_FVR\_BUF2}$**	**FVR Buffer 2 (DAC/CMP)**	**—**	**60.0**	**85.0**	**101.0**	**µA**	**3.0V**	**`'bx1` or `'b10`**	
D205	I_{PD_BOR}	Brown-out Reset (BOR)	—	16.6	20.4	20.8	µA	3.0V	`'b11`	
D206	I_{PD_HLVD}	High/Low Voltage Detect (HLVD)	—	16.9	20.8	22.5	µA	3.0V	`'b11`	
D207	I_{PD_ADCA}	ADC - Active	—	483	789	790	µA	3.0V	`'bx1` or `'b10`	ADC is converting **(Note 4)**
D208	I_{PD_CMP}	Comparator	—	52.5	84.2	105	µA	3.0V	`'b11`	

.....continued

Standard Operating Conditions (unless otherwise stated)										
Param. No.	Sym.	Device Characteristics	Min.	Typ.†	Max. +85°C	Max. +125°C	Units	Conditions		
								V_{DD}	VREGPM	Note
D209	I_{PD_OPA}	Operational Amplifier	—	1.10	1.67	1.73	mA	3.0V	'b01	Charge Pump On; V_{ICM} = V_{DD}/2
			—	**800**	**1160**	**1220**	**µA**	**3.0V**	**'b01**	**Charge Pump Off; V_{ICM} = V_{DD}/2**

* These parameters are characterized but not tested.

† Data in “Typ.” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Notes:

1. The peripheral current is the sum of the base I_{DD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max. values must be used when calculating total current consumption.
2. The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode with all I/O pins in high-impedance state and tied to V_{SS}.
3. All peripheral currents listed are on a per-peripheral basis if more than one instance of a peripheral is available.
4. ADC clock source is ADCRC.

3. Appendix A: Revision History

Doc Rev.	Date	Comments
E	04/2022	Updating the flash memory cell endurance specification datasheet clarification. Adding silicon erratum item 1.7.1
D	02/2022	Adding silicon revision A6. Adding silicon erratum items 1.1.2, 1.3.2, 1.5.1 and 1.6.1
C	11/2020	Adding silicon revision A5.
B	08/2020	Adding silicon erratum item 1.5.1.
A	06/2020	Initial document release.

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